

ABSTRACT

An electroplating apparatus and a cleaning method are disclosed. The electroplating apparatus comprises: a substrate holder including a holder main body, a conductive contact, and a sealing member, wherein the bottom portion of the holder main body extends radially inward to form a substrate support portion, the sealing member is disposed on the surface of the substrate support portion and protrudes upward at the end of the substrate support portion to form a sealing lip, and the sealing member and/or the holder main body are provided with a groove on the radially outward side of the sealing lip for accommodating the conductive contact; a cleaning system configured to inject cleaning liquid into the groove to immerse and clean the conductive contact; and a control system configured to control the substrate holder and the cleaning system to periodically perform immersion cleaning and spin-drying treatments on the conductive contact, thereby improving the cleaning effect of the substrate holder.